

Amendments to the Specification:

On page 1 of the application, please insert the following section prior to the section captioned "BACKGROUND":

RELATED APPLICATIONS

The present application is a continuation of U.S. Application Serial No. 10/340,256 entitled MOUNTING FOR A PACKAGE CONTAINING A CHIP filed January 10, 2003, which is a continuation of U.S. Application Serial No. 09/813,485 entitled MOUNTING FOR A PACKAGE CONTAINING A CHIP filed March 20, 2001 and issued as U.S. Patent No. 6,545,345 on April 8, 2003.

Please amend the paragraph beginning on page 5, line 15 and ending on page 5, line 19 as follows:

Body 24 has a first surface 24(a), an opposite planar second surface 24(b), and peripheral side surfaces ~~26e~~ 24c. Typically, body 24 may be formed by molding or pouring and then curing a resin material (e.g., an epoxy resin). Where body 24 is molded, as in this example, side surfaces ~~26e~~ 24c typically will be tapered to accommodate release from the mold.